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English Version

**Circuit boards and circuit board assemblies - Design and use -
Part 6-3: Land pattern design - Description of land pattern for
through hole components (THT)
(IEC 61188-6-3:2024)**

Cartes imprimées et cartes imprimées équipées -
Conception et utilisation - Partie 6-3: Conception de la zone
de report - Description de la zone de report pour les
composants à trous traversants (THT)
(IEC 61188-6-3:2024)

Leiterplatten und Flachbaugruppen - Konstruktion und
Anwendung - Teil 6-3: Anschlussflächengestaltung -
Beschreibung von Anschlussflächen für Komponenten der
Steckmontage (THT)
(IEC 61188-6-3:2024)

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CEN-CENELEC Management Centre: Rue de la Science 23, B-1040 Brussels

EN IEC 61188-6-3:2025 (E)**European foreword**

The text of document 91/1982/FDIS, future edition 1 of IEC 61188-6-3, prepared by TC 91 "Electronics assembly technology" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN IEC 61188-6-3:2025.

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- latest date by which the national standards conflicting with the (dow) 2028-01-31 document have to be withdrawn

This document partially supersedes EN 61188-5-2:2003, EN 61188-5-3:2007, EN 61188-5-4:2007, EN 61188-5-5:2007, EN 61188-5-6:2003 and EN 61188-5-8:2008 and all of their amendments and corrigenda (if any).

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In the official version, for Bibliography, the following notes have to be added for the standard indicated:

IEC 61188-6-2	NOTE	Approved as EN IEC 61188-6-2
IEC 61191-1	NOTE	Approved as EN IEC 61191-1
IEC 61191-2	NOTE	Approved as EN 61191-2
IEC 61191-3	NOTE	Approved as EN 61191-3
IEC 61191-4	NOTE	Approved as EN 61191-4

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 Where an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cencenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 60194-2	-	Printed boards design, manufacture and assembly - Vocabulary - Part 2: Common usage in electronic technologies as well as printed board and electronic assembly technologies	-	-
IEC 60352-5	2020	Solderless connections - Part 5: Press-in connections - General requirements, test methods and practical guidance	EN IEC 60352-5	2020

[SIST EN IEC 61188-6-3:2025](https://standards.iteh.ai/catalog/standards/sist/3cdadde7-f9a8-492c-b2f1-843169367660/sist-en-iec-61188-6-3-2025)

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NORME INTERNATIONALE



**Circuit boards and circuit board assemblies – Design and use –
Part 6-3: Land pattern design – Description of land pattern for through hole
components (THT)**

**Cartes imprimées et cartes imprimées équipées – Conception et utilisation –
Partie 6-3: Conception de la zone de report – Description de la zone de report
pour les composants à trous traversants (THT) 2025**

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**CIRCUIT BOARDS AND CIRCUIT BOARD ASSEMBLIES –
DESIGN AND USE –****Part 6-3: Land pattern design –
Description of land pattern for through hole components (THT)**

FOREWORD

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IEC 61188-6-3 has been prepared by IEC technical committee 91: Electronics assembly technology. It is an International Standard.

This first edition partially cancels and replaces the IEC 61188-5 series of International Standards.

The significant technical changes with respect to the previous edition are listed in the Introduction and further detailed information and calculations can be found in Annex A.

